imall

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EVERLIGHT

DATASHEET

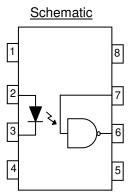
8 PIN DIP HIGH SPEED 10MBit/s LOGIC GATE PHOTOCOUPLER EL263X series





Features

- High speed 10Mbit/s
- 10kV/µs min. common mode transient immunity (EL2631)
- Guaranteed performance from -40 to 85° C
- Logic gate output
- High isolation voltage between input and output (Viso=5000 Vrms)
- Pb free and RoHS compliant.
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved



A 0.1 μF bypass capacitor must be connected between pins 8 and 5 \star3

Pin Configuration

- 1, No Connection
- 2, Anode
- 3, Cathode
- 4. No Connection
- 5, Gnd
- 6, Vout
- 7, V_E
- 8, V_{CC}

Description

The EL2630 and EL2631 are consists of an infrared emitting diode optically coupled to a high speed integrated photo detector logic gate with a strobable output. It is packaged in a 8-pin DIP package and available in wide-lead spacing and SMD options.

Applications

- Ground loop elimination
- LSTTL to TTL, LSTTL or 5 volt CMOS
- Line receiver, data transmission
- Data multiplexing
- Switching power supplies
- Pulse transformer replacement
- Computer peripheral interface
- High speed logic ground isolation

Truth Table (Positive Logic)

Input	Output
Н	L
L	Н

Absolute Maximum Ratings (T_A=25°C)

	Parameter	Symbol	Rating	Unit
	Forward current	l _F	20	mA
Input	Reverse voltage	V _R	5	V
	Power dissipation	P _D	40	mW
	Power dissipation	P _C	60	mW
Outeut	Output current	Ι _Ο	50	mA
Output	Output voltage	Vo	7.0	V
	Supply voltage	V _{CC}	7.0	V
Output Po	ower Dissipation	Po	85	mW
Isolation v	voltage ^{*1}	V _{ISO}	5000	Vrms
Operating	temperature	T _{OPR}	-40~+100	°C
Storage te	emperature	T _{STG}	-55~+125	°C
Soldering	temperature *2	T _{SOL}	260	°C

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3 & 4 are shorted together, and pins 5, 6, 7 & 8 are shorted together.

*2 For 10 seconds.

Electrical Characteristics (T_A =-40 to 85°C unless specified otherwise)

Input						
Parameter	Symbol	Min.	Тур.*	Max.	Unit	Condition
Forward voltage	V _F	-	1.4	1.8	V	I _F = 10mA, T _A =25°C
Reverse voltage	V_{R}	5.0	-	-	V	$I_R = 10 \mu A$
Temperature coefficient of forward voltage	$\Delta V_{F} / \Delta T_{A}$	-	-1.8	-	mV/°C	I _F =10mA
Input capacitance	C _{IN}	-	60	-	pF	$V_F=0, f=1MHz$
Output						
Parameter	Symbol	Min	Тур.*	Max.	Unit	Condition
High level supply current	I _{CCH}	-	12.5	18	mA	I _F =0mA, V _{CC} =5.5V
Low level supply current	I _{CCL}	-	14.5	21	mA	I_F =10mA, V_{CC} =5.5V

Transfer Characteristics (T_A =-40 to 85°C unless specified otherwise)

Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
HIGH Level Output Current	I _{OH}	-	2.1	100	μA	V _{CC} =5.5V, V _O =5.5V, I _F =250µA
LOW Level Output Current	V_{OL}	-	0.35	0.6	V	V_{CC} = 5.5V, I _F =5mA, I _{CL} =13mA
Input Threshold Current	I _{FT}	-	2.5	5	mA	V_{CC} = 5.5V, V_{O} =0.6V, I_{OL} =13mA

Switching Characteristics (T_A =-40 to 85°C, V_{CC}=5V, I_F=7.5mA unless specified otherwise)

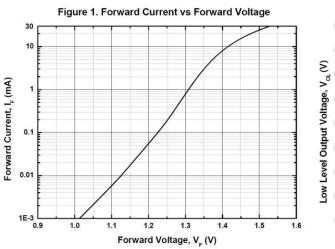
Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
Propagation delay time to output High level* ⁴ (Fig.12)	T _{PLH}	-	35	100	ns	$C_L = 15 pF, R_L = 350 \Omega,$ $T_A = 25^{\circ}C$
Propagation delay time to output Low level* ⁵ (Fig.12)	T _{PHL}	-	40	100	ns	$C_L = 15 pF, R_L = 350\Omega,$ $T_A = 25^{\circ}C$
Pulse width distortion	T _{PHL} –T _{PLH}	-	5	35	ns	$C_{L} = 15 pF, R_{L} = 350 \Omega$
Output rise time* ⁶ (Fig.12)	t _r	-	40	-	ns	$C_L = 15 pF, R_L = 350 \Omega$
Output fall time* ⁷ (Fig.12)	t _f	-	10	-	ns	$C_L = 15 pF, R_L = 350 \Omega$

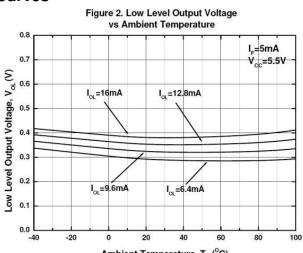
Switching Characteristics (T_A =-40 to 85°C, V_{CC}=5V, I_F=7.5mA unless specified otherwise)

Parameter		Symbol	Min	Тур.	Max.	Unit	Condition
Common Mode Transient Immunity at Logic High ^{*8}	EL2630	- CM	5,000	-	-	- V/μS	$ I_{F} = 0mA, V_{CM} = 1KV_{p-p}, \\ V_{OH} = 2.0V, R_{L} = 350\Omega, \\ T_{A} = 25^{\circ}C(Fig.13) $
	EL2631	– CM _H	10,000	20,000	-		$ I_{F} = 0mA , V_{CM} = 1KV_{p-p}, \\ V_{OH} = 2.0V, R_{L} = 350\Omega, \\ T_{A} = 25^{\circ}C(Fig.13) $
Common Mode Transient Immunity at Logic Low ^{*9}	EL2630	- CML	5,000	-	-	- V/μS	$ I_F = 7.5 mA, V_{CM} = 1 K V_{p-p}, \\ V_{OL} = 0.8 V, R_L = 350 \Omega, \\ T_A = 25^{\circ} C(Fig. 13) $
	EL2631		10,000	20,000	-		$I_{F} = 7.5 \text{mA}, V_{CM} = 1 \text{KV}_{\text{p-p}}, V_{OL} = 0.8 \text{V}, \text{R}_{L} = 350 \Omega, T_{A} = 25^{\circ} \text{C}(\text{Fig.13})$

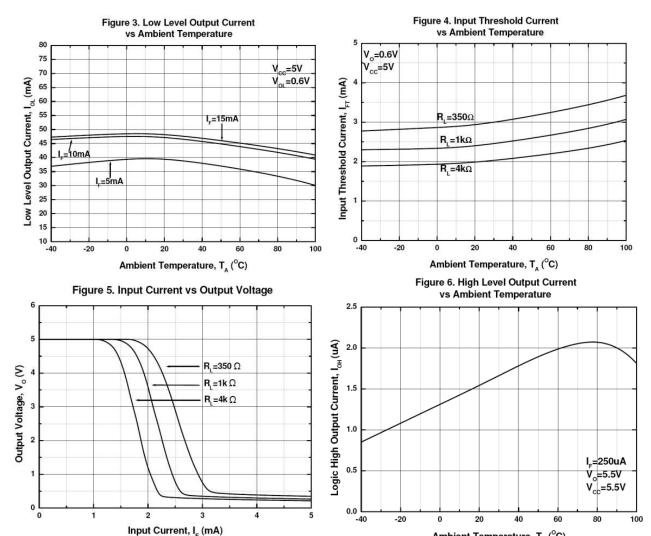


Typical Electro-Optical Characteristics Curves





Ambient Temperature, T, (°C)



Ambient Temperature, T₄ (°C)

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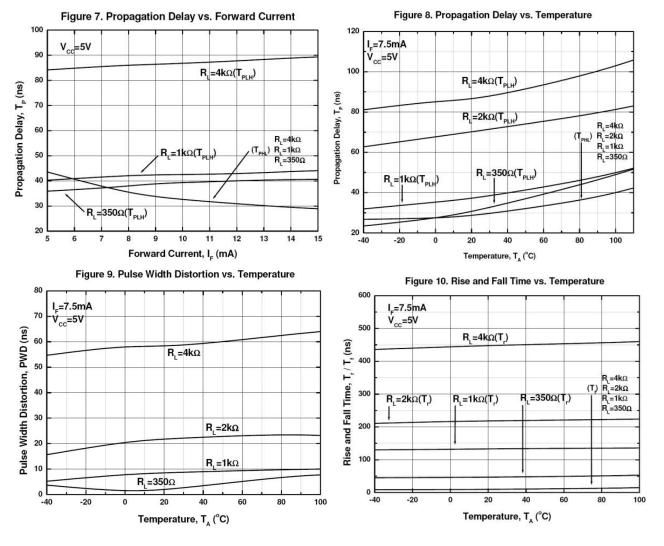
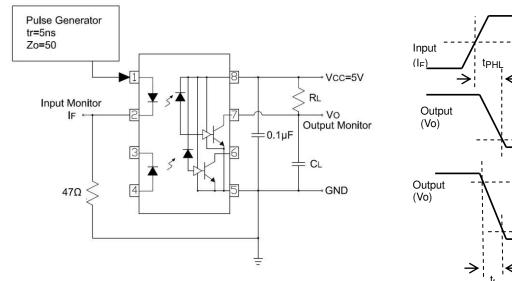
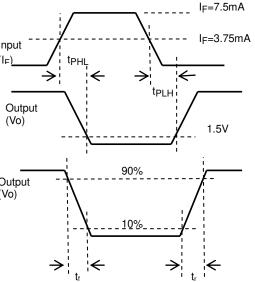


Fig. 11 Test circuit and waveforms for tPHL, tPLH, tr, and tf





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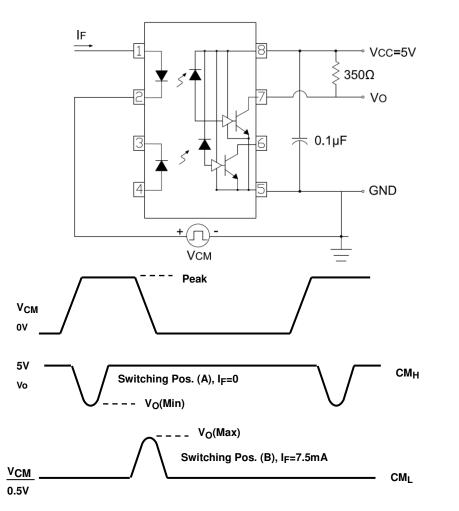


Fig. 12 Test circuit Common mode Transient Immunity

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Note

- *3 The VCC supply must be bypassed by a 0.1µF capacitor or larger. This can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to the package VCC and GND pins
- *4. tPLH Propagation delay is measured from the 3.75mA level on the HIGH to LOW transition of the input current pulse to the 1.5 V level on the LOW to HIGH transition of the output voltage pulse.
- *5. tPHL Propagation delay is measured from the 3.75mA level on the LOW to HIGH transition of the input current pulse to the 1.5 V level on the HIGH to LOW transition of the output voltage pulse.
- *6. tr Rise time is measured from the 90% to the 10% levels on the LOW to HIGH transition of the output pulse.
- *7. tf Fall time is measured from the 10% to the 90% levels on the HIGH to LOW transition of the output pulse.
- *8 CMH– The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the HIGH state (i.e., VOUT > 2.0V).
- *9 CML– The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the LOW output state (i.e., VOUT < 0.8V).



Order Information

Part Number

EL263XY(Z)-V

Note

- X Y = (0 or 1) for EL26 part no.
- = Lead form option (S, S1, M or none)
- Ζ = Tape and reel option (TA, TB or none).
- V = VDE (optional)

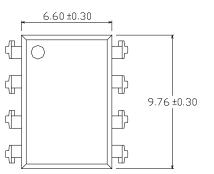
Option	Description	Packing quantity
None	Standard DIP-8	45 units per tube
М	Wide lead bend (0.4 inch spacing)	45 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

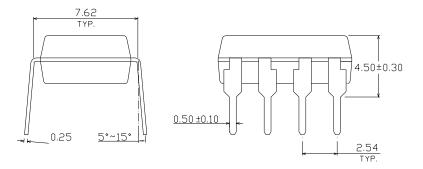
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Package Dimension

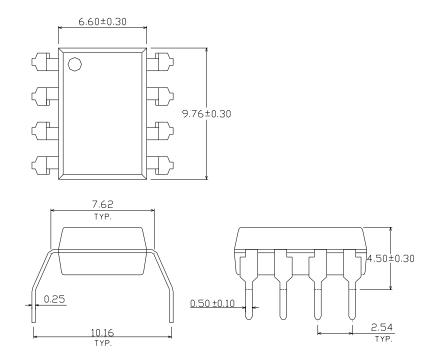
(Dimensions in mm)

Standard DIP Type





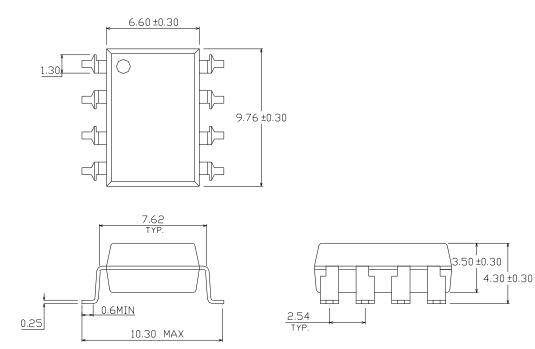
Option M Type



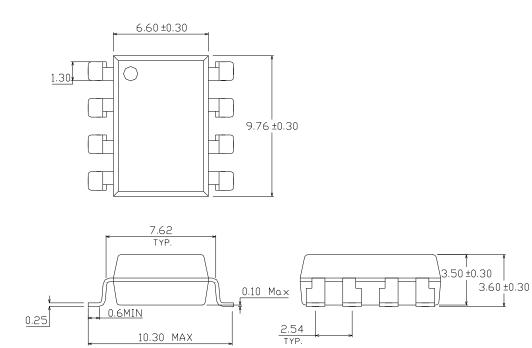
DATASHEET 8 PIN DIP HIGH SPEED 10MBit/s LOGIC GATE PHOTOCOUPLER EL263X series



Option S Type

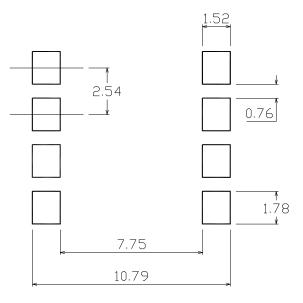


Option S1 Type

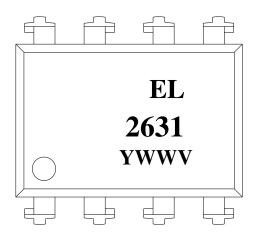




Recommended pad layout for surface mount leadform



Device Marking

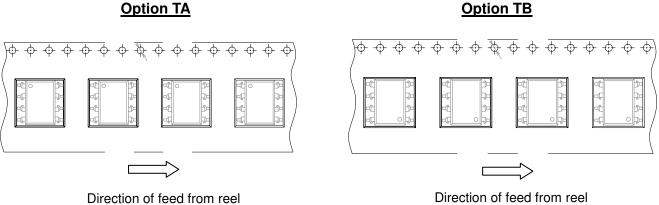


Notes

EL	denotes EVERLIGHT
2631	denotes Device Number
Υ	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)

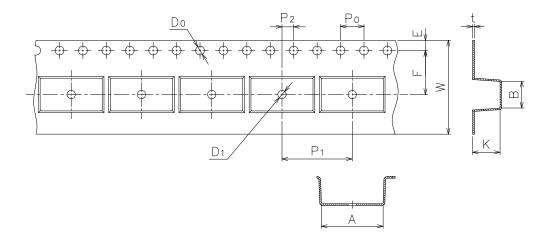


Tape & Reel Packing Specifications



Direction of feed from reel

Tape dimension



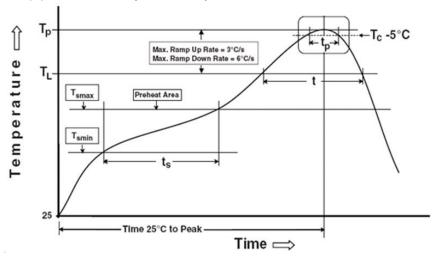
Dimension No.	Α	В	Do	D1	E	F
Dimension(mm)	10.4±0.1	10.0±0.1	1.5+0.1/-0	1.5±0.25/-0	1.75±0.1	7.5±0.1
Dimension No.	Ро	P1	P2	t	W	к
Dimension(mm)	4.0±0.1	12.0±0.1	2.0±0.05	0.4±0.05	16.0±0.3/	4.5±0.1



Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Preheat

Temperature min (T_{smin}) Temperature max (T_{smax}) Time $(T_{smin} \text{ to } T_{smax})$ (t_s) Average ramp-up rate $(T_{smax} \text{ to } T_p)$

Other

Liquidus Temperature (T_L) Time above Liquidus Temperature (t_L) Peak Temperature (T_P) Time within 5 °C of Actual Peak Temperature: T_P - 5°C Ramp- Down Rate from Peak Temperature Time 25°C to peak temperature Reflow times Reference: IPC/JEDEC J-STD-020D

150°C 200°C 60-120 seconds 3°C/second max

217°C 60-100 sec 260°C 30 s 6°C /second max. 8 minutes max. 3 times

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- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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